1:9 TTL Clock Driver

The MC10H645 is a single supply, low skew, TTL I/O 1:9 Clock Driver. Devices in the Motorola H600 clock driver family utilize the 28–lead PLCC for optimal power and signal pin placement.

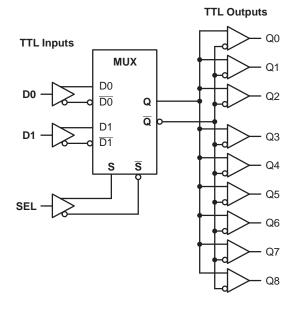
The device features a 24mA TTL ouput stage with AC performance specified into a 50pF load capacitance. A 2:1 input mux is provided on chip to allow for distributing both system and diagnostic clock signals or designing clock redundancy into a system. With the SEL input held LOW the DO input will be selected, while the D1 input is selected when the SEL input is forced HIGH.

- Low Skew Typically 0.65ns Within Device
- Guaranteed Skew Spec 1.25ns Part-to-Part
- Input Clock Muxing
- Differential ECL Internal Design
- Single Supply
- Extra TTL and ECL Power/Ground Pins

PIN NAMES

PIN	FUNCTION
GT	TTL Ground (0V)
VT	TTL V _{CC} (+5.0V)
VE	ECL V _{CC} (+5.0V)
GE	ECL Ground (0V)
Dn	TTL Signal Input
Q0 – Q8	TTL Signal Outputs
SEL	TTL Mux Select

LOGIC DIAGRAM



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PLCC-28 FN SUFFIX CASE 776





A = Assembly Location

WL = Wafer Lot

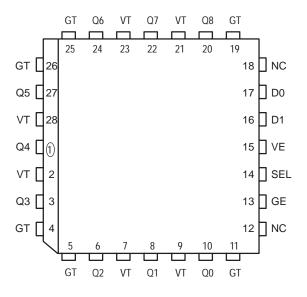
YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H645FN	PLCC-28	37 Units/Rail
MC100H645FN	PLCC-28	37 Units/Rail

Pinout: 28-Lead PLCC (Top View)



PIN DESCRIPTIONS

Pin	Symbol	Description	Pin	Symbol	Description
1	Q4	Signal Output (TTL)	15	VE	ECL V _{CC} (+5.0V)
2	VT	TTL V _{CC} (+5.0V)	16	D1	Signal Input (TTL)
3	Q3	Signal Output (TTL)	17	D0	Signal Input (TTL)
4	GT	TTL Ground (0V)	18	NC	No Connection
5	GT	TTL Ground (0V)	19	GT	TTL Ground (0V)
6	Q2	Signal Output (TTL)	20	Q8	Signal Output (TTL)
7	VT	TTL V _{CC} (+5.0V)	21	VT	TTL V _{CC} (+5.0V)
8	Q1	Signal Output (TTL)	22	Q7	Signal Output (TTL)
9	VT	TTL V _{CC} (+5.0V)	23	VT	TTL V _{CC} (+5.0V)
10	Q0	Signal Output (TTL)	24	Q6	Signal Output (TTL)
11	GT	TTL Ground (0V)	25	GT	TTL Ground (0V)
12	NC	No Connection '	26	GT	TTL Ground (OV)
13	GE	ECL Ground	27	Q5	Signal Output (TTL)
14	SEL	Select Input (TTL)	28	VT	TTL V _{CC} (+5.0V)

TRUTH TABLE

D0	D1	SEL	Q
L	X	L	L
H	X	L	H
X	L	H	L

ABSOLUTE RATINGS (Do not exceed)

Symbol	Characteristic	Value	Unit
VE (ECL)	Power Supply Voltage	−0.5 to +7.0	V
VT (TTL)	Power Supply Voltage	-0.5 to +7.0	V
VI (TTL)	Input Voltage	-0.5 to +7.0	V
V _{out}	Disabled 3-State Output	0.0 to V _T	V
T _{stg}	Storage Temperature	-65 to 150	°C
T _{amb}	Operating Temperature	0.0 to +85	°C

DC CHARACTERISTICS (VT = VE = $5.0V \pm 5\%$)

				0°C		25°C		85°C		
Symbol	Characteristic	;	Min	Max	Min	Max	Min	Max	Unit	Condition
IEE	Power Supply Current	ECL		30		30		30	mA	VE Pin
ICCH		TTL		30		30		30	mA	Total all VT pins
ICCL				35		35		35	mA	
VOH	Output HIGH Voltage		2.5 2.0		2.5 2.0		2.5 2.0		V	I _{OH} = -3.0mA I _{OH} = -15mA
V _{OL}	Output LOW Voltage			0.5		0.5		0.5	V	I _{OL} = 24mA
los	Output Short Circuit Curre	ent	-100	-225	-100	-225	-100	-225	mA	V _{OUT} = 0V

TTL DC CHARACTERISTICS (VT = VE = $5.0 \text{ V} \pm 5\%$)

		0°C		25°C		85°C			
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit	Condition
VIH VIL	Input HIGH Voltage Input LOW Voltage	2.0	0.8	2.0	0.8	2.0	0.8	V	
lН	Input HIGH Current		20 100		20 100		20 100	μА	V _{IN} = 2.7 V V _{IN} = 7.0 V
I _{IL}	Input LOW Current		-0.6		-0.6		-0.6	mA	V _{IN} = 0.5 V
Vон	Output HIGH Voltage	2.5 2.0		2.5 2.0		2.5 2.0		V	I _{OH} = -3.0 mA I _{OH} = -24 mA
VOL	Output LOW Voltage		0.5		0.5		0.5	V	I _{OL} = 24 mA
VIK	Input Clamp Voltage		-1.2		-1.2		-1.2	V	I _{IN} = -18 mA
los	Output Short Circuit Current	-100	-225	-100	-225	-100	-225	mA	VOUT = 0 V

AC CHARACTERISTICS (VT = VE = $5.0V \pm 5\%$)

			0	C	25	°C	85	°C		
Symbol	Characteristic	С	Min	Max	Min	Max	Min	Max	Unit	Condition
^t PLH	Propagation Delay D ₀ to Output Only	Q0-Q8	4.8	5.8	4.8	5.8	5.2	6.2	ns	CL = 50pF
^t PLH	Propagation Delay D ₁ to Output		4.8	5.8	4.8	5.8	5.2	6.2	ns	
^t PHL	Propagation Delay D ₀ to Output D ₁ to Output		4.8 4.8	5.8 5.8	4.8 4.8	5.8 5.8	5.2 5.2	6.2 6.2	ns	
^t skpp	Part–to–Part Skew D ₀ to Output Only			1.0		1.0		1.0	ns	
^t skwd [*]	Within–Device Skew D ₀ to Output Only			0.65		0.65		0.65	ns	
^t PLH	Propagation Delay SEL to Q	Q0–Q8	4.5	6.5	5.0	7.0	5.2	7.2	ns	CL = 50pF
t _r t _f	Output Rise/Fall Time 0.8V to 2.0V	Q0-Q8	0.5 0.5	2.5 2.5	0.5 0.5	2.5 2.5	0.5 0.5	2.5 2.5	ns	CL = 50pF
ts	Setup Time SEL to D		1.0		1.0		1.0		ns	

^{*} Within–Device Skew defined as identical transitions on similar paths through a device.

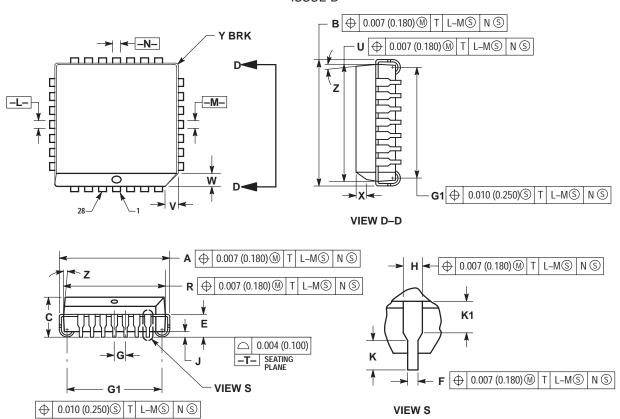
DUTY CYCLE SPECIFICATIONS ($0^{\circ}C \le TA \le 85^{\circ}C$; Duty Cycle Measured Relative to 1.5V)

Symbol	Characteristic		Min	Nom	Max	Unit	Condition
PW	Range of V _{CC} and CL to Meet Min Pulse Width (HIGH or LOW) at f _{Out} ≤50MHz	VCC CL PW	4.875 10.0 9.0	5.0	5.125 50.0 11.0	V pF ns	All Outputs

PACKAGE DIMENSIONS

PLCC-28 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 776-02 ISSUE D



NOTES

- IOTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH ALLOWABLE MOLD FLASH ALLOWABLE OLD FLASH SIO.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI Y14 SM 1982.
- ANSI Y14.5M, 1982.
 5. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST DELERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

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	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.485	0.495	12.32	12.57	
В	0.485	0.495	12.32	12.57	
С	0.165	0.180	4.20	4.57	
Е	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.450	0.456	11.43	11.58	
U	0.450	0.456	11.43	11.58	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Х	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10°	
G1	0.410	0.430	10.42	10.92	
K1	0.040		1.02		

Notes

Notes

Notes

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